

STYLE 1: STYLE 2: PIN 1. CATHODE CATHODE PIN 1. 2. COMMON DRAIN COMMON DRAIN 2. 3. CATHODE 3. COMMON DRAIN COMMON DRAIN COMMON DRAIN 4. 5. CATHODE 4. CATHODE 5. 6. CATHODE 6. COMMON DRAIN 7. CATHODE 7. COMMON DRAIN CATHODE COMMON DRAIN 8. 9. 8. 9. ANODE GATE 10. ANODE 10. SOURCE 11. 12. ANODE ANODE 11. 12. GATE SOURCE 13. ANODE 13. GATE 14. 15. ANODE ANODE 14. 15. SOURCE GATE 16. ANODE 16. SOURCE

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2
- 3.
- DIMENSIONING AND TOLERANGUIST FEA ADDING FEA 4.
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR 5. TO DATUM C
- DIMENSION 6B IS MEASURED AT THE LEAD TIPS WITH THE 6.
- LEADS UNCONSTRAINED. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE 7.
- LEADS, WHERE THE LEADS EXIT THE BODY. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE 8. CORNERS).

	INCHES MILLIMETER		ETERS	
DIM	MIN	MAX	MIN	MAX
Α		0.210		5.33
A1	0.015		0.38	
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
С	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005		0.13	
Е	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
е	0.100 BSC 2.54 BSC		BSC	
eB		0.430		10.92
L	0.115	0.150	2.92	3.81
Μ		10°		10°

GENERIC **MARKING DIAGRAM***

16	<u> </u>
	XXXXXXXXXXXXX
	D XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX
	O AWLYYWWG
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XXXXX = Specific Device Code

- = Assembly Location
- WL = Wafer Lot
- YΥ = Year

А

- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " .", may or may not be present.

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DATE 22 APR 2015





ISSUE	REVISION	DATE		
Т	ADDED MARKING DIAGRAM. REQ. BY S. FARRETTA	04 MAY 2004		
U	REDRAWN TO UNIFORM FABRICATION SITE SPECIFICATIONS. REQ. BY J. LETTERMAN.	05 JUN 2013		
V	CORRECTED DIMENSION REFERENCE IN NOTE 6 FROM E3 TO eB. REQ. BY JJ. YEOH.	22 APR 2015		

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